SOES028A – DECEMBER 1987 – REVISED APRIL 1998

- 400-V Phototriac Driver Output
- Gallium-Arsenide-Diode Infrared Source and Optically-Coupled Silicon Triac Driver (Bilateral Switch)
- UL Recognized ... File Number E65085
- High Isolation ... 3535 V peak
- Output Driver Designed for 220 Vac
- Standard 6-Pin Plastic DIP

typical 115/240 Vac(rms) applications

- Solenoid/Valve Controls
- Lamp Ballasts
- Interfacing Microprocessors to 115/240 Vac Peripherals
- Motor Controls
- Incandescent Lamp Dimmers

description

Each device consists of a gallium-arsenide infrared-emitting diode optically coupled to a silicon phototriac mounted on a 6-pin lead frame encapsulated within an electrically nonconductive plastic compound. The case withstands soldering temperature with no deformation. Device performance characteristics remain stable when operated in high-humidity conditions.

absolute maximum ratings at 25°C free-air (unless otherwise noted)[†]

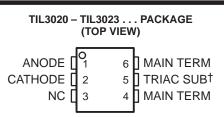
Input-to-output peak voltage, 5 s maximum duration, 60 Hz (see Note 1)	
Input diode forward current, continuous	
Output repetitive peak off-state voltage	
Output on-state current, total rms value (50-60 Hz, full sine wave): $T_A = 25^{\circ}C$	
$T_A = 70^{\circ}C$	
Output driver nonrepetitive peak on-state current ($t_w = 10$ ms, duty cycle = 10%, see Figure	re 7) 1.2 A
Continuous power dissipation at (or below) 25°C free-air temperature:	
Infrared-emitting diode (see Note 2)	100 mW
Phototriac (see Note 3)	300 mW
Total device (see Note 4)	
Operating junction temperature range, T _J	–40°C to 100°C
Storage temperature range, T _{stg}	–40°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Input-to-output peak voltage is the internal device dielectric breakdown rating.
 - 2. Derate linearly to 100°C free-air temperature at the rate of 1.33 mW/°C.
 - 3. Derate linearly to 100°C free-air temperature at the rate of 4 mW/°C.
 - 4. Derate linearly to 100°C free-air temperature at the rate of 4.4 mW/°C.

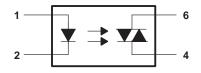


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[†] Do not connect this terminal NC – No internal connection

logic diagram



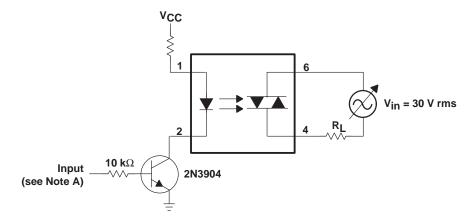
SOES028A - DECEMBER 1987 - REVISED APRIL 1998

electrical characteristics 25°C free-air temperature range (unless otherwise noted)

	PARAMETER		TEST COM	NDITIONS	MIN	TYP	MAX	UNIT
I _R	Static reverse current		V _R = 3 V			0.05	100	μA
VF	Static forward voltage		I _F = 10 mA			1.2	1.5	V
IDRM	DRM Repetitive off-state current, either direction		V _{DRM} = 400 V,	See Note 5		10	100	nA
dv/dt	Critical rate of rise of off-state voltage		See Figure 1			100		V/µs
dv/dt(c)	Critical rate of rise of communication voltage		I _O = 15 mA,	See Figure 1		0.15		V/µs
IFT	Input trigger current, either direction	TIL3020	Output supply voltage = 3 V		15	30	mA	
		TIL3021			8	15		
		TIL3022			5	10		
		TIL3023			3	5		
VTM	Peak on-state voltage, either direction		I _{TM} = 100 mA			1.4	3	V
Ι _Η	Holding current, either direction					100		μA

NOTE 5: Test voltage must be applied at a rate no higher than 12 V/µs.

PARAMETER MEASUREMENT INFORMATION



NOTE A. The critical rate of rise of off-state voltage, dv/dt, is measured with the input set at 0 volts. The frequency of V_{in} is increased until the phototriac turns on. This frequency is then used to calculate the dv/dt according to the following formula:

$$dv/dt = 2\sqrt{2\pi fV}_{in}$$

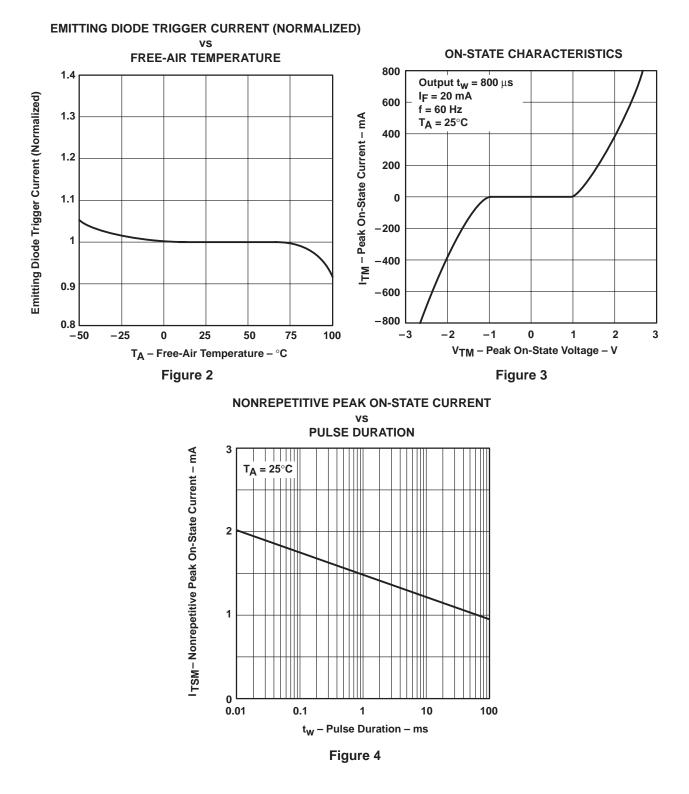
The critical rate of rise of commutating voltage, dv/dt(c), is measured by applying occasional 5-volt pulses to the input and increasing the frequency of V_{in} until the phototriac remains on (latches) after the input pulse has ceased. With no further input pulses, the frequency of V_{in} is then gradually decreased until the phototriac turns off. The frequency at which turn-off occurs can then be used to calculate the dv/dt(c) according to the formula shown above.

Figure 1. Critical Rate of Rise Test Circuit



SOES028A – DECEMBER 1987 – REVISED APRIL 1998

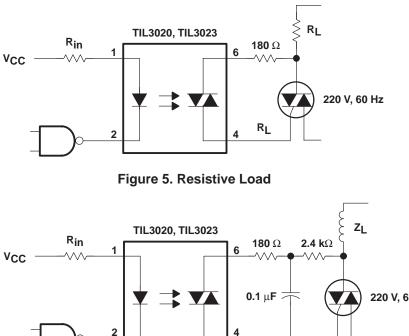
TYPICAL CHARACTERISTICS

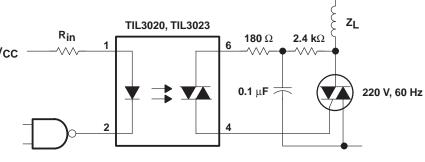




SOES028A - DECEMBER 1987 - REVISED APRIL 1998

APPLICATION INFORMATION





 $I_{GT} \le 15 \text{ mA}$

Figure 6. Inductive Load With Sensitive-Gate Traic

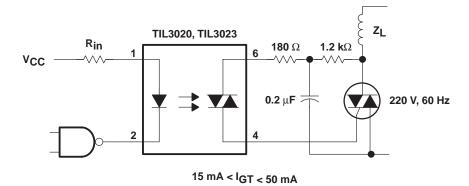
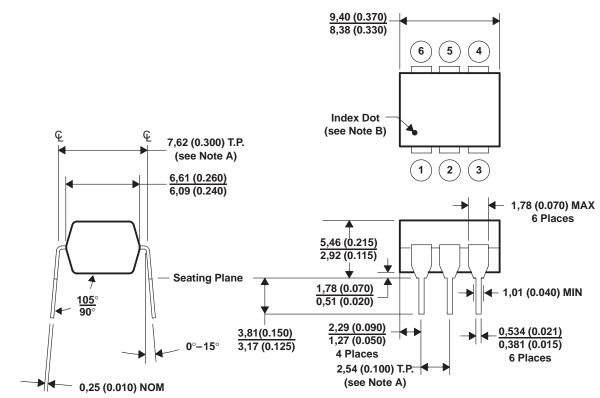


Figure 7. Inductive Load With Nonsensitive-Gate Triac



SOES028A - DECEMBER 1987 - REVISED APRIL 1998

MECHANICAL INFORMATION



NOTES: A. Leads are within 0,13 (0.005) radius of true position (T.P.) with maximum material condition and unit installed.

- B. Pin 1 identified by index dot.
 - C. The dimensions given fall within JEDEC MO-001 AM dimensions.
 - D. All linear dimensions are given in millimeters and parenthetically given in inches.

Figure 8. Packaging Specifications



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